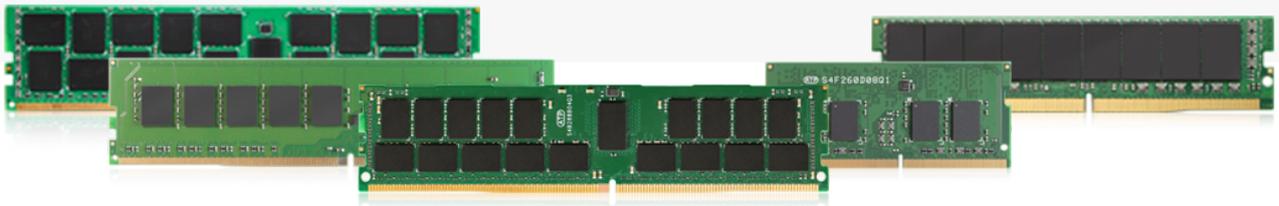




DDR4

The Global Leader in Specialized Storage and Memory Solutions



Key Features

- Density: 2 GB to 256 GB
- Increased performance and bandwidth (up to 3200 MT/s)
- Decreased voltage for better power consumption
- Provides better reliability, availability and serviceability (RAS) and improves data integrity

ATP's fourth-generation industrial DDR memory combines up to 3200 MT/s data transfer rate and a mere 1.2V power consumption to deliver faster performance at higher power savings over earlier DRAM technologies.

As the evolutionary transition from DDR3, DDR4 supports features and functions that are well-suited for increasing bandwidth capabilities to support the growth of online traffic.

DDR4-3200 MT/s is the newest generation of fast, performance-oriented DRAM modules optimized for the latest Intel® Xeon® Platinum, Gold, Silver and Bronze Scalable processors and 8th-generation Intel® Core™ i7/i5/i3 processors. The increased interface speed from 2400 MT/s to 3200 MT/s amplifies theoretical peak performance by 20% and gives a boost to the most critical computing applications in industries such as telecommunication infrastructures, networking storage systems, network-attached storage (NAS) servers, micro/cloud servers, and embedded systems like industrial PCs.

Technologies & Add-On Services	30µm Golden Finger	ATP TDBI	Wide Temperature	Anti-Sulfur Resistors	Conformal Coating	PCB Chamfer
RDIMM	●	●	▲	▲	—	▲
ECC UDIMM	●	●	▲	▲	▲	▲
Non-ECC UDIMM	●	●	▲	▲	▲	▲
ECC SO-DIMM	●	●	▲	▲	▲	▲
Non-ECC SO-DIMM	●	●	▲	▲	▲	▲
Mini-RDIMM	●	●	▲	▲	—	—
Mini-UDIMM	●	●	▲	▲	—	—

▲: Optional

Specifications

DDR4							
DIMM Type	RDIMM	ECC UDIMM	Non-ECC UDIMM	ECC SO-DIMM	Non-ECC SO-DIMM	Mini-RDIMM	Mini-UDIMM
Density	4 GB to 256 GB	4 GB to 32 GB	2 GB to 32 GB	4 GB to 32 GB	2 GB to 32 GB	4 GB to 16 GB	
Speed up to (MT/s)	3200					2400	
PCB Height*	Low profile / VLP / ULP			Low profile		Low profile / VLP	VLP
Operating Temperature	0°C to 85°C / -40°C to 85°C						

* VLP: 0.74", ULP: below 0.74"

Hot Items Ordering Information					
SPEED	SIZE	CHIP	HEIGHT	Ranks	P/N
Unb/Non ECC SO-DIMM DDR4-3200	4 GB	512x16	1.18"	1	A4G04QC6BNWEMO
	8 GB	1Gx16	1.18"	1	A4G08QC6BVWEMO
	16 GB	2GX8	1.18"	1	A4G16QA8BVWEMO
	32 GB	2GX8	1.18"	2	A4G32QE8BVWEMO
Unb/Non ECC SO-DIMM DDR4-2666	4 GB	512x16	1.18"	1	A4G04QC6BNTDMO
	8 GB	1Gx16	1.18"	1	A4G08QC6BVTDMO
	16 GB	2GX8	1.18"	1	A4G16QA8BVTDMO
	32 GB	2GX8	1.18"	2	A4G32QE8BVTDMO

Product spec and its related information are subject to change without advance notice.
Please refer to www.atpinc.com for latest information

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